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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

|                                |                                                                                                                                         |
|--------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------|
| Product Status                 | Obsolete                                                                                                                                |
| Number of LABs/CLBs            | 196                                                                                                                                     |
| Number of Logic Elements/Cells | 466                                                                                                                                     |
| Total RAM Bits                 | 6272                                                                                                                                    |
| Number of I/O                  | 77                                                                                                                                      |
| Number of Gates                | 5000                                                                                                                                    |
| Voltage - Supply               | 3V ~ 3.6V                                                                                                                               |
| Mounting Type                  | Surface Mount                                                                                                                           |
| Operating Temperature          | -40°C ~ 100°C (TJ)                                                                                                                      |
| Package / Case                 | 100-TQFP                                                                                                                                |
| Supplier Device Package        | 100-VQFP (14x14)                                                                                                                        |
| Purchase URL                   | <a href="https://www.e-xfl.com/product-detail/xilinx/xc4005xl-2vq100i">https://www.e-xfl.com/product-detail/xilinx/xc4005xl-2vq100i</a> |

**Table 1: XC4000E and XC4000X Series Field Programmable Gate Arrays**

| Device      | Logic Cells | Max Logic Gates (No RAM) | Max. RAM Bits (No Logic) | Typical Gate Range (Logic and RAM)* | CLB Matrix | Total CLBs | Number of Flip-Flops | Max. User I/O |
|-------------|-------------|--------------------------|--------------------------|-------------------------------------|------------|------------|----------------------|---------------|
| XC4002XL    | 152         | 1,600                    | 2,048                    | 1,000 - 3,000                       | 8 x 8      | 64         | 256                  | 64            |
| XC4003E     | 238         | 3,000                    | 3,200                    | 2,000 - 5,000                       | 10 x 10    | 100        | 360                  | 80            |
| XC4005E/XL  | 466         | 5,000                    | 6,272                    | 3,000 - 9,000                       | 14 x 14    | 196        | 616                  | 112           |
| XC4006E     | 608         | 6,000                    | 8,192                    | 4,000 - 12,000                      | 16 x 16    | 256        | 768                  | 128           |
| XC4008E     | 770         | 8,000                    | 10,368                   | 6,000 - 15,000                      | 18 x 18    | 324        | 936                  | 144           |
| XC4010E/XL  | 950         | 10,000                   | 12,800                   | 7,000 - 20,000                      | 20 x 20    | 400        | 1,120                | 160           |
| XC4013E/XL  | 1368        | 13,000                   | 18,432                   | 10,000 - 30,000                     | 24 x 24    | 576        | 1,536                | 192           |
| XC4020E/XL  | 1862        | 20,000                   | 25,088                   | 13,000 - 40,000                     | 28 x 28    | 784        | 2,016                | 224           |
| XC4025E     | 2432        | 25,000                   | 32,768                   | 15,000 - 45,000                     | 32 x 32    | 1,024      | 2,560                | 256           |
| XC4028EX/XL | 2432        | 28,000                   | 32,768                   | 18,000 - 50,000                     | 32 x 32    | 1,024      | 2,560                | 256           |
| XC4036EX/XL | 3078        | 36,000                   | 41,472                   | 22,000 - 65,000                     | 36 x 36    | 1,296      | 3,168                | 288           |
| XC4044XL    | 3800        | 44,000                   | 51,200                   | 27,000 - 80,000                     | 40 x 40    | 1,600      | 3,840                | 320           |
| XC4052XL    | 4598        | 52,000                   | 61,952                   | 33,000 - 100,000                    | 44 x 44    | 1,936      | 4,576                | 352           |
| XC4062XL    | 5472        | 62,000                   | 73,728                   | 40,000 - 130,000                    | 48 x 48    | 2,304      | 5,376                | 384           |
| XC4085XL    | 7448        | 85,000                   | 100,352                  | 55,000 - 180,000                    | 56 x 56    | 3,136      | 7,168                | 448           |

\* Max values of Typical Gate Range include 20-30% of CLBs used as RAM.

**Note:** All functionality in low-voltage families is the same as in the corresponding 5-Volt family, except where numerical references are made to timing or power.

## Description

XC4000 Series devices are implemented with a regular, flexible, programmable architecture of Configurable Logic Blocks (CLBs), interconnected by a powerful hierarchy of versatile routing resources, and surrounded by a perimeter of programmable Input/Output Blocks (IOBs). They have generous routing resources to accommodate the most complex interconnect patterns.

The devices are customized by loading configuration data into internal memory cells. The FPGA can either actively read its configuration data from an external serial or byte-parallel PROM (master modes), or the configuration data can be written into the FPGA from an external device (slave and peripheral modes).

XC4000 Series FPGAs are supported by powerful and sophisticated software, covering every aspect of design from schematic or behavioral entry, floor planning, simulation, automatic block placement and routing of interconnects, to the creation, downloading, and readback of the configuration bit stream.

Because Xilinx FPGAs can be reprogrammed an unlimited number of times, they can be used in innovative designs

where hardware is changed dynamically, or where hardware must be adapted to different user applications. FPGAs are ideal for shortening design and development cycles, and also offer a cost-effective solution for production rates well beyond 5,000 systems per month.

## Taking Advantage of Re-configuration

FPGA devices can be re-configured to change logic function while resident in the system. This capability gives the system designer a new degree of freedom not available with any other type of logic.

Hardware can be changed as easily as software. Design updates or modifications are easy, and can be made to products already in the field. An FPGA can even be re-configured dynamically to perform different functions at different times.

Re-configurable logic can be used to implement system self-diagnostics, create systems capable of being re-configured for different environments or operations, or implement multi-purpose hardware for a given application. As an added benefit, using re-configurable FPGA devices simplifies hardware design and debugging and shortens product time-to-market.

### ***Input Thresholds***

The input thresholds of 5V devices can be globally configured for either TTL (1.2 V threshold) or CMOS (2.5 V threshold), just like XC2000 and XC3000 inputs. The two global adjustments of input threshold and output level are independent of each other. The XC4000XL family has an input threshold of 1.6V, compatible with both 3.3V CMOS and TTL levels.

### ***Global Signal Access to Logic***

There is additional access from global clocks to the F and G function generator inputs.

### ***Configuration Pin Pull-Up Resistors***

During configuration, these pins have weak pull-up resistors. For the most popular configuration mode, Slave Serial, the mode pins can thus be left unconnected. The three mode inputs can be individually configured with or without weak pull-up or pull-down resistors. A pull-down resistor value of 4.7 k $\Omega$  is recommended.

The three mode inputs can be individually configured with or without weak pull-up or pull-down resistors after configuration.

The PROGRAM input pin has a permanent weak pull-up.

### ***Soft Start-up***

Like the XC3000A, XC4000 Series devices have "Soft Start-up." When the configuration process is finished and the device starts up, the first activation of the outputs is automatically slew-rate limited. This feature avoids potential ground bounce when all outputs are turned on simultaneously. Immediately after start-up, the slew rate of the individual outputs is, as in the XC4000 family, determined by the individual configuration option.

### ***XC4000 and XC4000A Compatibility***

Existing XC4000 bitstreams can be used to configure an XC4000E device. XC4000A bitstreams must be recompiled for use with the XC4000E due to improved routing resources, although the devices are pin-for-pin compatible.

## **Additional Improvements in XC4000X Only**

### ***Increased Routing***

New interconnect in the XC4000X includes twenty-two additional vertical lines in each column of CLBs and twelve new horizontal lines in each row of CLBs. The twelve "Quad Lines" in each CLB row and column include optional repowering buffers for maximum speed. Additional high-performance routing near the IOBs enhances pin flexibility.

### ***Faster Input and Output***

A fast, dedicated early clock sourced by global clock buffers is available for the IOBs. To ensure synchronization with the regular global clocks, a Fast Capture latch driven by the early clock is available. The input data can be initially loaded into the Fast Capture latch with the early clock, then transferred to the input flip-flop or latch with the low-skew global clock. A programmable delay on the input can be used to avoid hold-time requirements. See ["IOB Input Signals" on page 20](#) for more information.

### ***Latch Capability in CLBs***

Storage elements in the XC4000X CLB can be configured as either flip-flops or latches. This capability makes the FPGA highly synthesis-compatible.

### ***IOB Output MUX From Output Clock***

A multiplexer in the IOB allows the output clock to select either the output data or the IOB clock enable as the output to the pad. Thus, two different data signals can share a single output pad, effectively doubling the number of device outputs without requiring a larger, more expensive package. This multiplexer can also be configured as an AND-gate to implement a very fast pin-to-pin path. See ["IOB Output Signals" on page 23](#) for more information.

### ***Additional Address Bits***

Larger devices require more bits of configuration data. A daisy chain of several large XC4000X devices may require a PROM that cannot be addressed by the eighteen address bits supported in the XC4000E. The XC4000X Series therefore extends the addressing in Master Parallel configuration mode to 22 bits.

## Set/Reset

An asynchronous storage element input (SR) can be configured as either set or reset. This configuration option determines the state in which each flip-flop becomes operational after configuration. It also determines the effect of a Global Set/Reset pulse during normal operation, and the effect of a pulse on the SR pin of the CLB. All three set/reset functions for any single flip-flop are controlled by the same configuration data bit.

The set/reset state can be independently specified for each flip-flop. This input can also be independently disabled for either flip-flop.

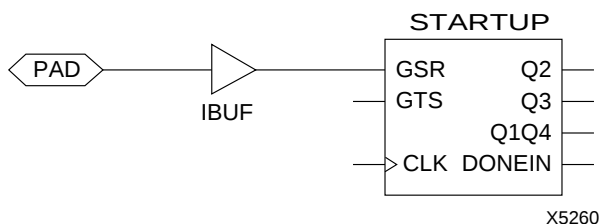
The set/reset state is specified by using the INIT attribute, or by placing the appropriate set or reset flip-flop library symbol.

SR is active High. It is not invertible within the CLB.

## Global Set/Reset

A separate Global Set/Reset line (not shown in Figure 1) sets or clears each storage element during power-up, re-configuration, or when a dedicated Reset net is driven active. This global net (GSR) does not compete with other routing resources; it uses a dedicated distribution network.

Each flip-flop is configured as either globally set or reset in the same way that the local set/reset (SR) is specified. Therefore, if a flip-flop is set by SR, it is also set by GSR. Similarly, a reset flip-flop is reset by both SR and GSR.



**Figure 2: Schematic Symbols for Global Set/Reset**

GSR can be driven from any user-programmable pin as a global reset input. To use this global net, place an input pad and input buffer in the schematic or HDL code, driving the GSR pin of the STARTUP symbol. (See Figure 2.) A specific pin location can be assigned to this input using a LOC attribute or property, just as with any other user-programmable pad. An inverter can optionally be inserted after the input buffer to invert the sense of the Global Set/Reset signal.

Alternatively, GSR can be driven from any internal node.

## Data Inputs and Outputs

The source of a storage element data input is programmable. It is driven by any of the functions F', G', and H', or by the Direct In (DIN) block input. The flip-flops or latches drive the XQ and YQ CLB outputs.

Two fast feed-through paths are available, as shown in Figure 1. A two-to-one multiplexer on each of the XQ and YQ outputs selects between a storage element output and any of the control inputs. This bypass is sometimes used by the automated router to repower internal signals.

## Control Signals

Multiplexers in the CLB map the four control inputs (C1 - C4 in Figure 1) into the four internal control signals (H1, DIN/H2, SR/H0, and EC). Any of these inputs can drive any of the four internal control signals.

When the logic function is enabled, the four inputs are:

- EC — Enable Clock
- SR/H0 — Asynchronous Set/Reset or H function generator Input 0
- DIN/H2 — Direct In or H function generator Input 2
- H1 — H function generator Input 1.

When the memory function is enabled, the four inputs are:

- EC — Enable Clock
- WE — Write Enable
- D0 — Data Input to F and/or G function generator
- D1 — Data input to G function generator (16x1 and 16x2 modes) or 5th Address bit (32x1 mode).

## Using FPGA Flip-Flops and Latches

The abundance of flip-flops in the XC4000 Series invites pipelined designs. This is a powerful way of increasing performance by breaking the function into smaller subfunctions and executing them in parallel, passing on the results through pipeline flip-flops. This method should be seriously considered wherever throughput is more important than latency.

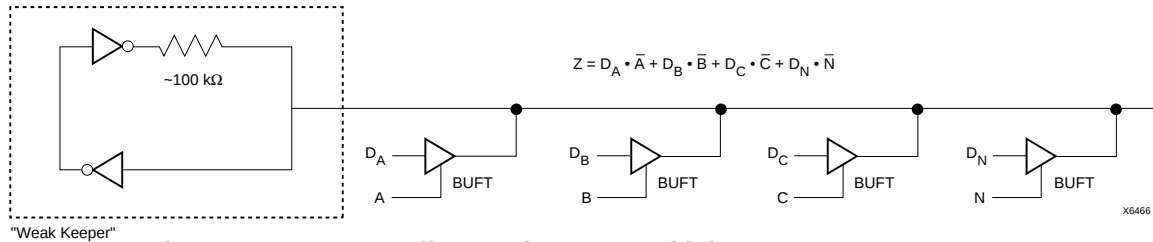
To include a CLB flip-flop, place the appropriate library symbol. For example, FDCE is a D-type flip-flop with clock enable and asynchronous clear. The corresponding latch symbol (for the XC4000X only) is called LDCE.

In XC4000 Series devices, the flip flops can be used as registers or shift registers without blocking the function generators from performing a different, perhaps unrelated task. This ability increases the functional capacity of the devices.

The CLB setup time is specified between the function generator inputs and the clock input K. Therefore, the specified CLB flip-flop setup time includes the delay through the function generator.

## Using Function Generators as RAM

Optional modes for each CLB make the memory look-up tables in the F' and G' function generators usable as an array of Read/Write memory cells. Available modes are level-sensitive (similar to the XC4000/A/H families), edge-triggered, and dual-port edge-triggered. Depending on the selected mode, a single CLB can be configured as either a 16x2, 32x1, or 16x1 bit array.



**Figure 22: 3-State Buffers Implement a Multiplexer**

## Wide Edge Decoders

Dedicated decoder circuitry boosts the performance of wide decoding functions. When the address or data field is wider than the function generator inputs, FPGAs need multi-level decoding and are thus slower than PALs. XC4000 Series CLBs have nine inputs. Any decoder of up to nine inputs is, therefore, compact and fast. However, there is also a need for much wider decoders, especially for address decoding in large microprocessor systems.

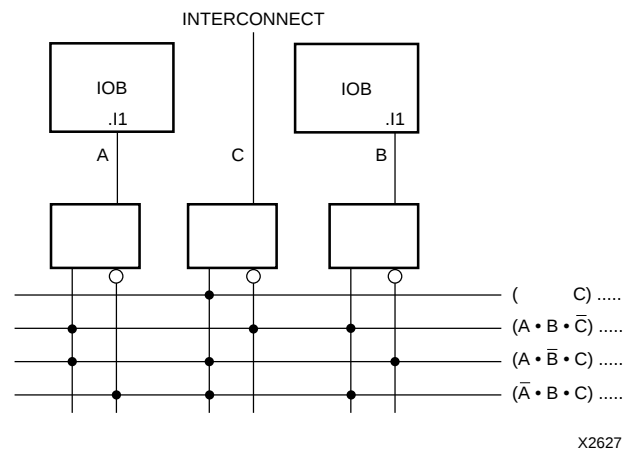
An XC4000 Series FPGA has four programmable decoders located on each edge of the device. The inputs to each decoder are any of the IOB I1 signals on that edge plus one local interconnect per CLB row or column. Each row or column of CLBs provides up to three variables or their complements., as shown in Figure 23. Each decoder generates a High output (resistor pull-up) when the AND condition of the selected inputs, or their complements, is true. This is analogous to a product term in typical PAL devices.

Each of these wired-AND gates is capable of accepting up to 42 inputs on the XC4005E and 72 on the XC4013E. There are up to 96 inputs for each decoder on the XC4028X and 132 on the XC4052X. The decoders may also be split in two when a larger number of narrower decoders are required, for a maximum of 32 decoders per device.

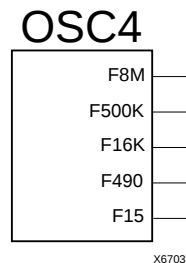
The decoder outputs can drive CLB inputs, so they can be combined with other logic to form a PAL-like AND/OR structure. The decoder outputs can also be routed directly to the chip outputs. For fastest speed, the output should be on the same chip edge as the decoder. Very large PALs can be emulated by ORing the decoder outputs in a CLB. This decoding feature covers what has long been considered a weakness of older FPGAs. Users often resorted to external PALs for simple but fast decoding functions. Now, the dedicated decoders in the XC4000 Series device can implement these functions fast and efficiently.

To use the wide edge decoders, place one or more of the WAND library symbols (WAND1, WAND4, WAND8, WAND16). Attach a DECODE attribute or property to each WAND symbol. Tie the outputs together and attach a PUL-

LUP symbol. Location attributes or properties such as L (left edge) or TR (right half of top edge) should also be used to ensure the correct placement of the decoder inputs.



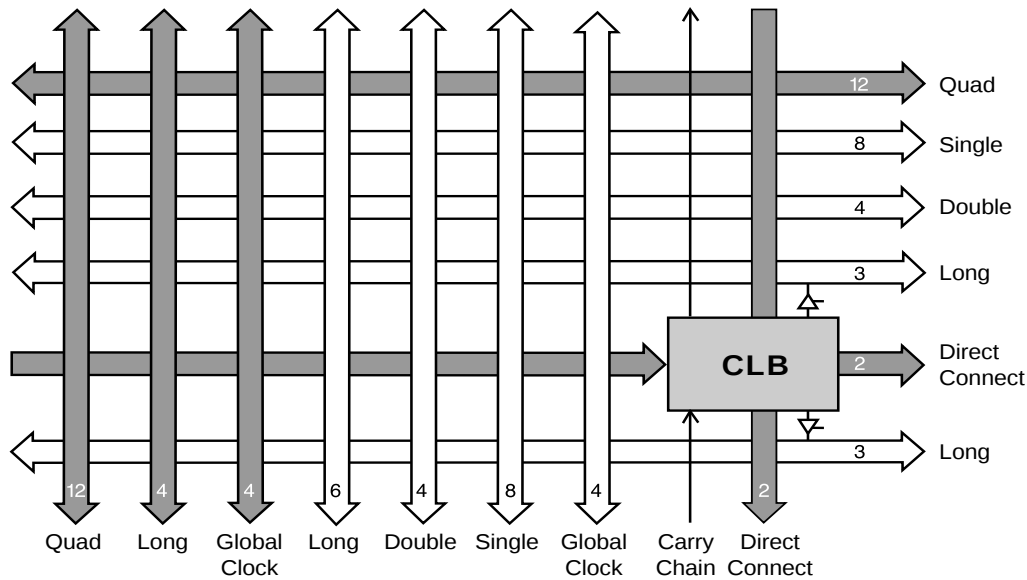
**Figure 23: XC4000 Series Edge Decoding Example**



**Figure 24: XC4000 Series Oscillator Symbol**

## On-Chip Oscillator

XC4000 Series devices include an internal oscillator. This oscillator is used to clock the power-on time-out, for configuration memory clearing, and as the source of CCLK in Master configuration modes. The oscillator runs at a nominal 8 MHz frequency that varies with process, Vcc, and temperature. The output frequency falls between 4 and 10 MHz.



x5994

**Figure 25: High-Level Routing Diagram of XC4000 Series CLB (shaded arrows indicate XC4000X only)**

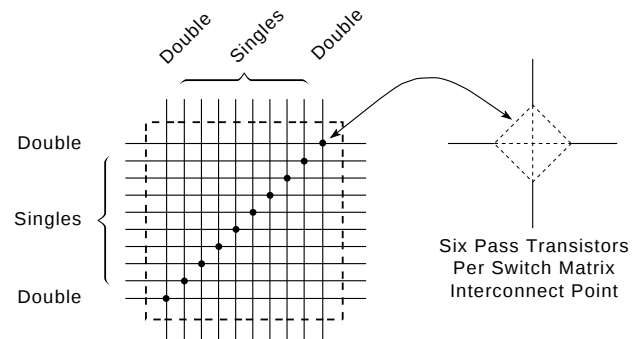
**Table 14: Routing per CLB in XC4000 Series Devices**

|                 | XC4000E  |            | XC4000X  |            |
|-----------------|----------|------------|----------|------------|
|                 | Vertical | Horizontal | Vertical | Horizontal |
| Singles         | 8        | 8          | 8        | 8          |
| Doubles         | 4        | 4          | 4        | 4          |
| Quads           | 0        | 0          | 12       | 12         |
| Longlines       | 6        | 6          | 10       | 6          |
| Direct Connects | 0        | 0          | 2        | 2          |
| Globals         | 4        | 0          | 8        | 0          |
| Carry Logic     | 2        | 0          | 1        | 0          |
| Total           | 24       | 18         | 45       | 32         |

### Programmable Switch Matrices

The horizontal and vertical single- and double-length lines intersect at a box called a programmable switch matrix (PSM). Each switch matrix consists of programmable pass transistors used to establish connections between the lines (see Figure 26).

For example, a single-length signal entering on the right side of the switch matrix can be routed to a single-length line on the top, left, or bottom sides, or any combination thereof, if multiple branches are required. Similarly, a double-length signal can be routed to a double-length line on any or all of the other three edges of the programmable switch matrix.



X6600

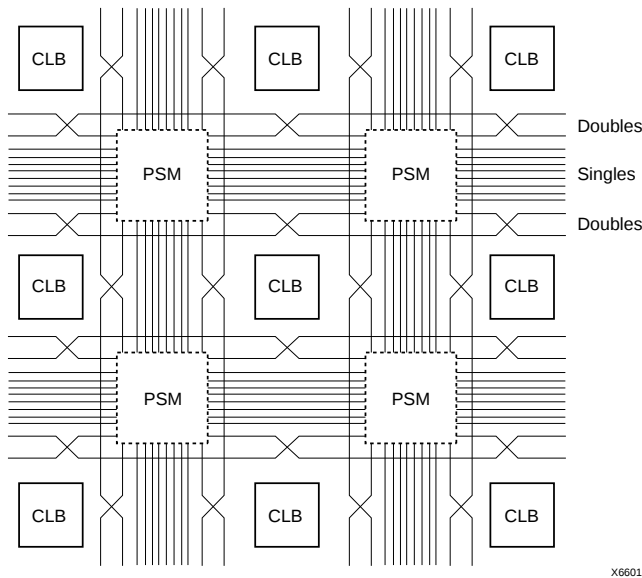
**Figure 26: Programmable Switch Matrix (PSM)**

### Single-Length Lines

Single-length lines provide the greatest interconnect flexibility and offer fast routing between adjacent blocks. There are eight vertical and eight horizontal single-length lines associated with each CLB. These lines connect the switching matrices that are located in every row and a column of CLBs.

Single-length lines are connected by way of the programmable switch matrices, as shown in Figure 28. Routing connectivity is shown in Figure 27.

Single-length lines incur a delay whenever they go through a switching matrix. Therefore, they are not suitable for routing signals for long distances. They are normally used to conduct signals within a localized area and to provide the branching for nets with fanout greater than one.



**Figure 28: Single- and Double-Length Lines, with Programmable Switch Matrices (PSMs)**

### Double-Length Lines

The double-length lines consist of a grid of metal segments, each twice as long as the single-length lines: they run past two CLBs before entering a switch matrix. Double-length lines are grouped in pairs with the switch matrices staggered, so that each line goes through a switch matrix at every other row or column of CLBs (see [Figure 28](#)).

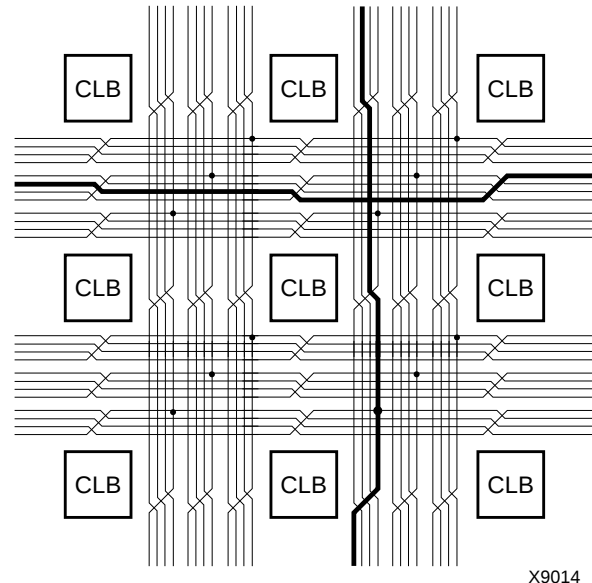
There are four vertical and four horizontal double-length lines associated with each CLB. These lines provide faster signal routing over intermediate distances, while retaining routing flexibility. Double-length lines are connected by way of the programmable switch matrices. Routing connectivity is shown in [Figure 27](#).

### Quad Lines (XC4000X only)

XC4000X devices also include twelve vertical and twelve horizontal quad lines per CLB row and column. Quad lines are four times as long as the single-length lines. They are interconnected via buffered switch matrices (shown as diamonds in [Figure 27 on page 30](#)). Quad lines run past four CLBs before entering a buffered switch matrix. They are grouped in fours, with the buffered switch matrices staggered, so that each line goes through a buffered switch matrix at every fourth CLB location in that row or column. (See [Figure 29](#).)

The buffered switch matrixes have four pins, one on each edge. All of the pins are bidirectional. Any pin can drive any or all of the other pins.

Each buffered switch matrix contains one buffer and six pass transistors. It resembles the programmable switch matrix shown in [Figure 26](#), with the addition of a programmable buffer. There can be up to two independent inputs



**Figure 29: Quad Lines (XC4000X only)**

and up to two independent outputs. Only one of the independent inputs can be buffered.

The place and route software automatically uses the timing requirements of the design to determine whether or not a quad line signal should be buffered. A heavily loaded signal is typically buffered, while a lightly loaded one is not. One scenario is to alternate buffers and pass transistors. This allows both vertical and horizontal quad lines to be buffered at alternating buffered switch matrices.

Due to the buffered switch matrices, quad lines are very fast. They provide the fastest available method of routing heavily loaded signals for long distances across the device.

### Longlines

Longlines form a grid of metal interconnect segments that run the entire length or width of the array. Longlines are intended for high fan-out, time-critical signal nets, or nets that are distributed over long distances. In XC4000X devices, quad lines are preferred for critical nets, because the buffered switch matrices make them faster for high fan-out nets.

Two horizontal longlines per CLB can be driven by 3-state or open-drain drivers (TBUFs). They can therefore implement unidirectional or bidirectional buses, wide multiplexers, or wired-AND functions. (See ["Three-State Buffers" on page 26](#) for more details.)

Each horizontal longline driven by TBUFs has either two (XC4000E) or eight (XC4000X) pull-up resistors. To activate these resistors, attach a PULLUP symbol to the long-line net. The software automatically activates the appropriate number of pull-ups. There is also a weak keeper at each end of these two horizontal longlines. This

### Global Nets and Buffers (XC4000X only)

Eight vertical longlines in each CLB column are driven by special global buffers. These longlines are in addition to the vertical longlines used for standard interconnect. The global lines are broken in the center of the array, to allow faster distribution and to minimize skew across the whole array. Each half-column global line has its own buffered multiplexer, as shown in [Figure 35](#). The top and bottom global lines cannot be connected across the center of the device, as this connection might introduce unacceptable skew. The top and bottom halves of the global lines must be separately driven — although they can be driven by the same global buffer.

The eight global lines in each CLB column can be driven by either of two types of global buffers. They can also be driven by internal logic, because they can be accessed by single, double, and quad lines at the top, bottom, half, and quarter points. Consequently, the number of different clocks that can be used simultaneously in an XC4000X device is very large.

There are four global lines feeding the IOBs at the left edge of the device. IOBs along the right edge have eight global lines. There is a single global line along the top and bottom edges with access to the IOBs. All IOB global lines are broken at the center. They cannot be connected across the center of the device, as this connection might introduce unacceptable skew.

IOB global lines can be driven from two types of global buffers, or from local interconnect. Alternatively, top and bottom IOBs can be clocked from the global lines in the adjacent CLB column.

Two different types of clock buffers are available in the XC4000X:

- Global Low-Skew Buffers (BUFGLS)
- Global Early Buffers (BUFGE)

Global Low-Skew Buffers are the standard clock buffers. They should be used for most internal clocking, whenever a large portion of the device must be driven.

Global Early Buffers are designed to provide a faster clock access, but CLB access is limited to one-fourth of the device. They also facilitate a faster I/O interface.

[Figure 35](#) is a conceptual diagram of the global net structure in the XC4000X.

Global Early buffers and Global Low-Skew buffers share a single pad. Therefore, the same IPAD symbol can drive one buffer of each type, in parallel. This configuration is particularly useful when using the Fast Capture latches, as described in [“IOB Input Signals” on page 20](#). Paired Global

Early and Global Low-Skew buffers share a common input; they cannot be driven by two different signals.

### Choosing an XC4000X Clock Buffer

The clocking structure of the XC4000X provides a large variety of features. However, it can be simple to use, without understanding all the details. The software automatically handles clocks, along with all other routing, when the appropriate clock buffer is placed in the design. In fact, if a buffer symbol called BUFG is placed, rather than a specific type of buffer, the software even chooses the buffer most appropriate for the design. The detailed information in this section is provided for those users who want a finer level of control over their designs.

If fine control is desired, use the following summary and [Table 15 on page 35](#) to choose an appropriate clock buffer.

- The simplest thing to do is to use a Global Low-Skew buffer.
- If a faster clock path is needed, try a BUFG. The software will first try to use a Global Low-Skew Buffer. If timing requirements are not met, a faster buffer will automatically be used.
- If a single quadrant of the chip is sufficient for the clocked logic, and the timing requires a faster clock than the Global Low-Skew buffer, use a Global Early buffer.

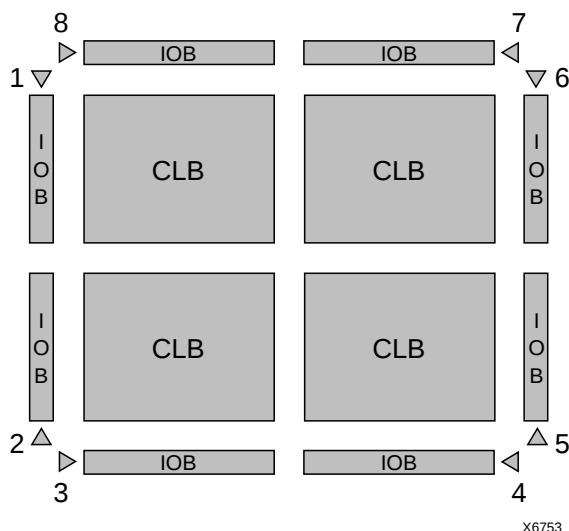
### Global Low-Skew Buffers

Each corner of the XC4000X device has two Global Low-Skew buffers. Any of the eight Global Low-Skew buffers can drive any of the eight vertical Global lines in a column of CLBs. In addition, any of the buffers can drive any of the four vertical lines accessing the IOBs on the left edge of the device, and any of the eight vertical lines accessing the IOBs on the right edge of the device. (See [Figure 36 on page 38](#).)

IOBs at the top and bottom edges of the device are accessed through the vertical Global lines in the CLB array, as in the XC4000E. Any Global Low-Skew buffer can, therefore, access every IOB and CLB in the device.

The Global Low-Skew buffers can be driven by either semi-dedicated pads or internal logic.

To use a Global Low-Skew buffer, instantiate a BUFGLS element in a schematic or in HDL code. If desired, attach a LOC attribute or property to direct placement to the designated location. For example, attach a LOC=T attribute or property to direct that a BUFGLS be placed in one of the two Global Low-Skew buffers on the top edge of the device, or a LOC=TR to indicate the Global Low-Skew buffer on the top edge of the device, on the right.



**Figure 36: Any BUFGLS (GCK1 - GCK8) Can Drive Any or All Clock Inputs on the Device**

### Global Early Buffers

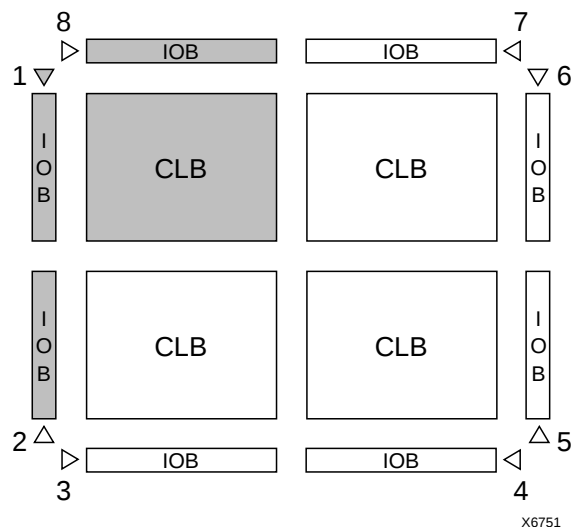
Each corner of the XC4000X device has two Global Early buffers. The primary purpose of the Global Early buffers is to provide an earlier clock access than the potentially heavily-loaded Global Low-Skew buffers. A clock source applied to both buffers will result in the Global Early clock edge occurring several nanoseconds earlier than the Global Low-Skew buffer clock edge, due to the lighter loading.

Global Early buffers also facilitate the fast capture of device inputs, using the Fast Capture latches described in **"IOB Input Signals"** on page 20. For Fast Capture, take a single clock signal, and route it through both a Global Early buffer and a Global Low-Skew buffer. (The two buffers share an input pad.) Use the Global Early buffer to clock the Fast Capture latch, and the Global Low-Skew buffer to clock the normal input flip-flop or latch, as shown in **Figure 17** on page 23.

The Global Early buffers can also be used to provide a fast Clock-to-Out on device output pins. However, an early clock in the output flip-flop IOB must be taken into consideration when calculating the internal clock speed for the design.

The Global Early buffers at the left and right edges of the chip have slightly different capabilities than the ones at the top and bottom. Refer to **Figure 37**, **Figure 38**, and **Figure 35** on page 36 while reading the following explanation.

Each Global Early buffer can access the eight vertical Global lines for all CLBs in the quadrant. Therefore, only one-fourth of the CLB clock pins can be accessed. This restriction is in large part responsible for the faster speed of the buffers, relative to the Global Low-Skew buffers.

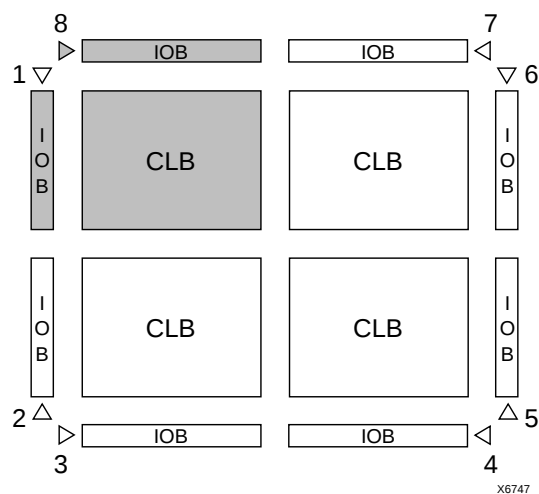


**Figure 37: Left and Right BUFGEs Can Drive Any or All Clock Inputs in Same Quadrant or Edge (GCK1 is shown. GCK2, GCK5 and GCK6 are similar.)**

The left-side Global Early buffers can each drive two of the four vertical lines accessing the IOBs on the entire left edge of the device. The right-side Global Early buffers can each drive two of the eight vertical lines accessing the IOBs on the entire right edge of the device. (See **Figure 37**.)

Each left and right Global Early buffer can also drive half of the IOBs along either the top or bottom edge of the device, using a dedicated line that can only be accessed through the Global Early buffers.

The top and bottom Global Early buffers can drive half of the IOBs along either the left or right edge of the device, as shown in **Figure 38**. They can only access the top and bottom IOBs via the CLB global lines.



**Figure 38: Top and Bottom BUFGEs Can Drive Any or All Clock Inputs in Same Quadrant (GCK8 is shown. GCK3, GCK4 and GCK7 are similar.)**

Figure 41 on page 44 is a diagram of the XC4000 Series boundary scan logic. It includes three bits of Data Register per IOB, the IEEE 1149.1 Test Access Port controller, and the Instruction Register with decodes.

XC4000 Series devices can also be configured through the boundary scan logic. See "Readback" on page 55.

## Data Registers

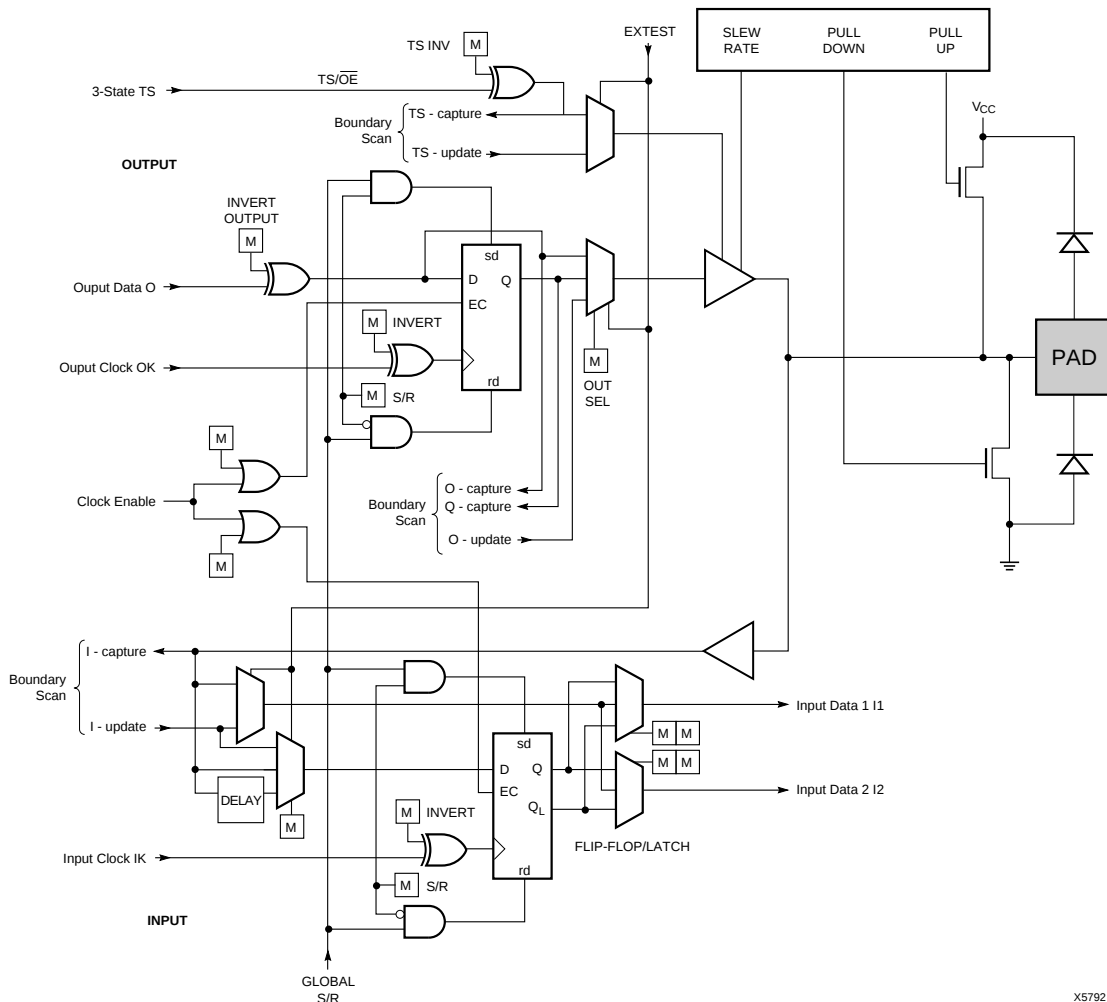
The primary data register is the boundary scan register. For each IOB pin in the FPGA, bonded or not, it includes three bits for In, Out and 3-State Control. Non-IOB pins have appropriate partial bit population for In or Out only. PROGRAM, CCLK and DONE are not included in the boundary scan register. Each EXTEST CAPTURE-DR state captures all In, Out, and 3-state pins.

The data register also includes the following non-pin bits: TDO.T, and TDO.O, which are always bits 0 and 1 of the

data register, respectively, and BSCANT.UPD, which is always the last bit of the data register. These three boundary scan bits are special-purpose Xilinx test signals.

The other standard data register is the single flip-flop BYPASS register. It synchronizes data being passed through the FPGA to the next downstream boundary scan device.

The FPGA provides two additional data registers that can be specified using the BSCAN macro. The FPGA provides two user pins (BSCAN.SEL1 and BSCAN.SEL2) which are the decodes of two user instructions. For these instructions, two corresponding pins (BSCAN.TDO1 and BSCAN.TDO2) allow user scan data to be shifted out on TDO. The data register clock (BSCAN.DRCK) is available for control of test logic which the user may wish to implement with CLBs. The NAND of TCK and RUN-TEST-IDLE is also provided (BSCAN.IDLE).



**Figure 40: Block Diagram of XC4000E IOB with Boundary Scan (some details not shown). XC4000X Boundary Scan Logic is Identical.**

is passed through and is captured by each FPGA when it recognizes the 0010 preamble. Following the length-count data, each FPGA outputs a High on DOUT until it has received its required number of data frames.

After an FPGA has received its configuration data, it passes on any additional frame start bits and configuration data on DOUT. When the total number of configuration clocks applied after memory initialization equals the value of the 24-bit length count, the FPGAs begin the start-up sequence and become operational together. FPGA I/O are normally released two CCLK cycles after the last configuration bit is received. **Figure 47 on page 53** shows the start-up timing for an XC4000 Series device.

The daisy-chained bitstream is not simply a concatenation of the individual bitstreams. The PROM file formatter must be used to combine the bitstreams for a daisy-chained configuration.

### Multi-Family Daisy Chain

All Xilinx FPGAs of the XC2000, XC3000, and XC4000 Series use a compatible bitstream format and can, therefore, be connected in a daisy chain in an arbitrary sequence. There is, however, one limitation. The lead device must belong to the highest family in the chain. If the chain contains XC4000 Series devices, the master normally cannot be an XC2000 or XC3000 device.

The reason for this rule is shown in **Figure 47 on page 53**. Since all devices in the chain store the same length count value and generate or receive one common sequence of CCLK pulses, they all recognize length-count match on the same CCLK edge, as indicated on the left edge of **Figure 47**. The master device then generates additional CCLK pulses until it reaches its finish point F. The different families generate or require different numbers of additional CCLK pulses until they reach F. Not reaching F means that the device does not really finish its configuration, although DONE may have gone High, the outputs became active, and the internal reset was released. For the XC4000 Series device, not reaching F means that readback cannot be ini-

tiated and most boundary scan instructions cannot be used.

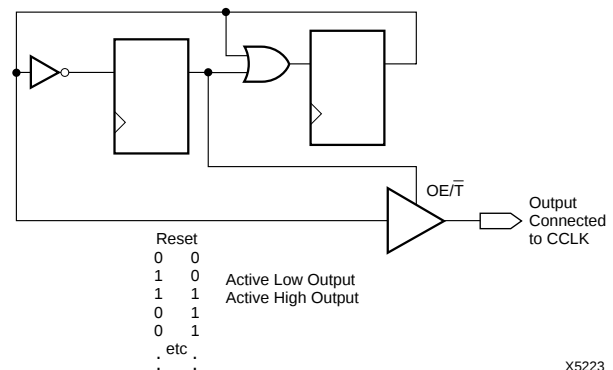
The user has some control over the relative timing of these events and can, therefore, make sure that they occur at the proper time and the finish point F is reached. Timing is controlled using options in the bitstream generation software.

### XC3000 Master with an XC4000 Series Slave

Some designers want to use an inexpensive lead device in peripheral mode and have the more precious I/O pins of the XC4000 Series devices all available for user I/O. **Figure 44** provides a solution for that case.

This solution requires one CLB, one IOB and pin, and an internal oscillator with a frequency of up to 5 MHz as a clock source. The XC3000 master device must be configured with late Internal Reset, which is the default option.

One CLB and one IOB in the lead XC3000-family device are used to generate the additional CCLK pulse required by the XC4000 Series devices. When the lead device removes the internal RESET signal, the 2-bit shift register responds to its clock input and generates an active Low output signal for the duration of the subsequent clock period. An external connection between this output and CCLK thus creates the extra CCLK pulse.



**Figure 44: CCLK Generation for XC3000 Master Driving an XC4000 Series Slave**

## Setting CCLK Frequency

For Master modes, CCLK can be generated in either of two frequencies. In the default slow mode, the frequency ranges from 0.5 MHz to 1.25 MHz for XC4000E and XC4000EX devices and from 0.6 MHz to 1.8 MHz for XC4000XL devices. In fast CCLK mode, the frequency ranges from 4 MHz to 10 MHz for XC4000E/EX devices and from 5 MHz to 15 MHz for XC4000XL devices. The frequency is selected by an option when running the bitstream generation software. If an XC4000 Series Master is driving an XC3000- or XC2000-family slave, slow CCLK mode must be used. In addition, an XC4000XL device driving a XC4000E or XC4000EX should use slow mode. Slow mode is the default.

**Table 19: XC4000 Series Data Stream Formats**

| Data Type                   | All Other Modes (D0...) |
|-----------------------------|-------------------------|
| Fill Byte                   | 11111111b               |
| Preamble Code               | 0010b                   |
| Length Count                | COUNT(23:0)             |
| Fill Bits                   | 1111b                   |
| Start Field                 | 0b                      |
| Data Frame                  | DATA(n-1:0)             |
| CRC or Constant Field Check | xxxx (CRC) or 0110b     |
| Extend Write Cycle          | —                       |
| Postamble                   | 01111111b               |
| Start-Up Bytes              | xxh                     |
| Legend:                     |                         |
| Not shaded                  | Once per bitstream      |
| Light                       | Once per data frame     |
| Dark                        | Once per device         |

## Data Stream Format

The data stream (“bitstream”) format is identical for all configuration modes.

The data stream formats are shown in [Table 19](#). Bit-serial data is read from left to right, and byte-parallel data is effectively assembled from this serial bitstream, with the first bit in each byte assigned to D0.

The configuration data stream begins with a string of eight ones, a preamble code, followed by a 24-bit length count and a separator field of ones. This header is followed by the actual configuration data in frames. The length and number of frames depends on the device type (see [Table 20](#) and [Table 21](#)). Each frame begins with a start field and ends with an error check. A postamble code is required to signal the end of data for a single device. In all cases, additional start-up bytes of data are required to provide four clocks for the startup sequence at the end of configuration. Long daisy chains require additional startup bytes to shift the last data through the chain. All startup bytes are don't-cares; these bytes are not included in bitstreams created by the Xilinx software.

A selection of CRC or non-CRC error checking is allowed by the bitstream generation software. The non-CRC error checking tests for a designated end-of-frame field for each frame. For CRC error checking, the software calculates a running CRC and inserts a unique four-bit partial check at the end of each frame. The 11-bit CRC check of the last frame of an FPGA includes the last seven data bits.

Detection of an error results in the suspension of data loading and the pulling down of the  $\overline{\text{INIT}}$  pin. In Master modes, CCLK and address signals continue to operate externally. The user must detect  $\overline{\text{INIT}}$  and initialize a new configuration by pulsing the  $\overline{\text{PROGRAM}}$  pin Low or cycling Vcc.

used), and if RAM is present, the RAM content must be unchanged.

Statistically, one error out of 2048 might go undetected.

## Configuration Sequence

There are four major steps in the XC4000 Series power-up configuration sequence.

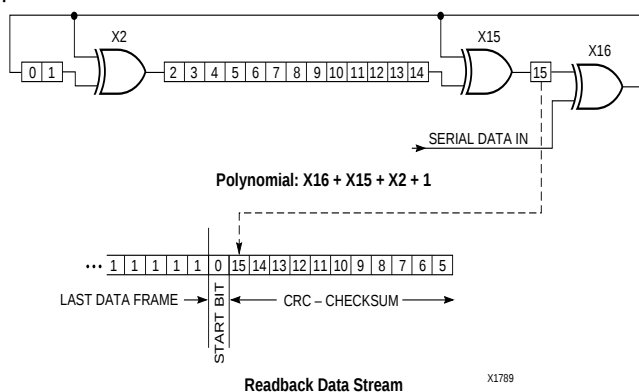
- Configuration Memory Clear
- Initialization
- Configuration
- Start-Up

The full process is illustrated in Figure 46.

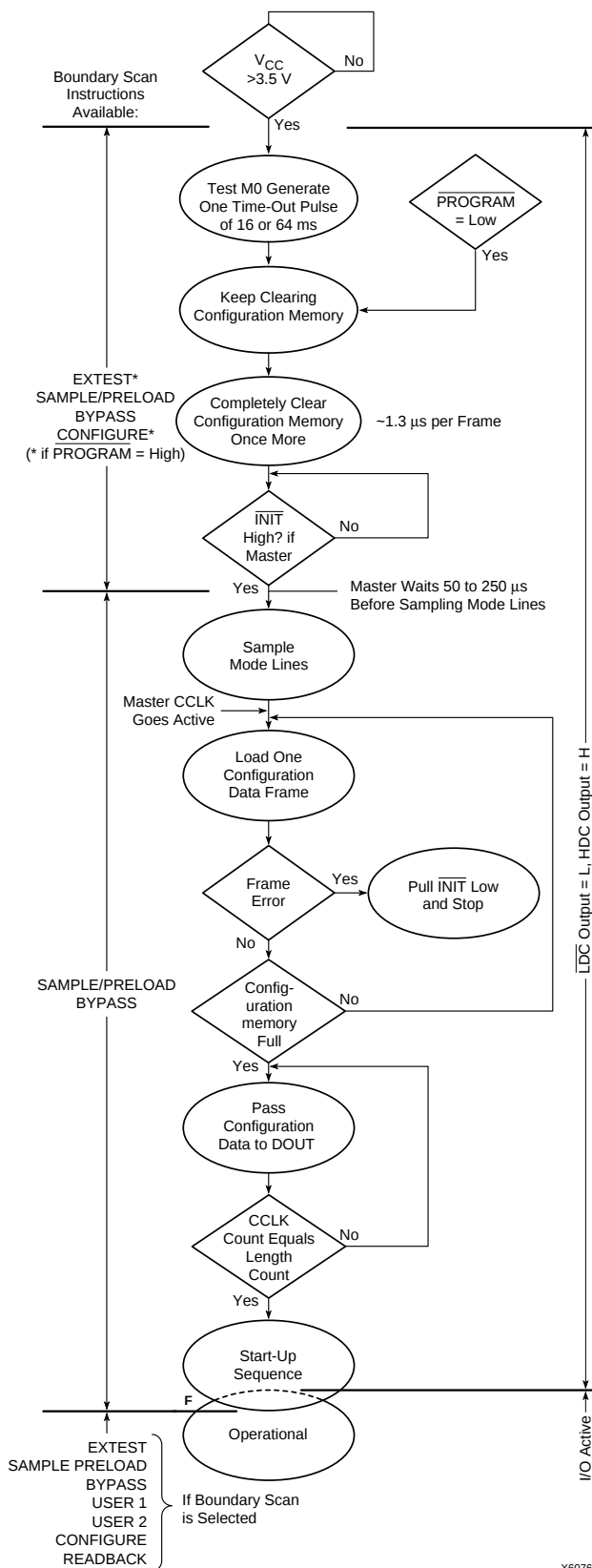
### Configuration Memory Clear

When power is first applied or is reapplied to an FPGA, an internal circuit forces initialization of the configuration logic. When  $V_{CC}$  reaches an operational level, and the circuit passes the write and read test of a sample pair of configuration bits, a time delay is started. This time delay is nominally 16 ms, and up to 10% longer in the low-voltage devices. The delay is four times as long when in Master Modes (M0 Low), to allow ample time for all slaves to reach a stable  $V_{CC}$ . When all  $\overline{INIT}$  pins are tied together, as recommended, the longest delay takes precedence. Therefore, devices with different time delays can easily be mixed and matched in a daisy chain.

This delay is applied only on power-up. It is not applied when re-configuring an FPGA by pulsing the  $\overline{PROGRAM}$  pin



**Figure 45: Circuit for Generating CRC-16**



**Figure 46: Power-up Configuration Sequence**

### **Start-up from a User Clock (STARTUP.CLK)**

When, instead of CCLK, a user-supplied start-up clock is selected, Q1 is used to bridge the unknown phase relationship between CCLK and the user clock. This arbitration causes an unavoidable one-cycle uncertainty in the timing of the rest of the start-up sequence.

### **DONE Goes High to Signal End of Configuration**

XC4000 Series devices read the expected length count from the bitstream and store it in an internal register. The length count varies according to the number of devices and the composition of the daisy chain. Each device also counts the number of CCLKs during configuration.

Two conditions have to be met in order for the DONE pin to go high:

- the chip's internal memory must be full, and
- the configuration length count must be met, *exactly*.

This is important because the counter that determines when the length count is met begins with the very first CCLK, not the first one after the preamble.

Therefore, if a stray bit is inserted before the preamble, or the data source is not ready at the time of the first CCLK, the internal counter that holds the number of CCLKs will be one ahead of the actual number of data bits read. At the end of configuration, the configuration memory will be full, but the number of bits in the internal counter will not match the expected length count.

As a consequence, a Master mode device will continue to send out CCLKs until the internal counter turns over to zero, and then reaches the correct length count a second time. This will take several seconds [ $2^{24} * \text{CCLK period}$ ] — which is sometimes interpreted as the device not configuring at all.

If it is not possible to have the data ready at the time of the first CCLK, the problem can be avoided by increasing the number in the length count by the appropriate value. The *XACT User Guide* includes detailed information about manually altering the length count.

Note that DONE is an open-drain output and does not go High unless an internal pull-up is activated or an external pull-up is attached. The internal pull-up is activated as the default by the bitstream generation software.

### **Release of User I/O After DONE Goes High**

By default, the user I/O are released one CCLK cycle after the DONE pin goes High. If CCLK is not clocked after DONE goes High, the outputs remain in their initial state — 3-stated, with a 50 k $\Omega$  - 100 k $\Omega$  pull-up. The delay from DONE High to active user I/O is controlled by an option to the bitstream generation software.

### **Release of Global Set/Reset After DONE Goes High**

By default, Global Set/Reset (GSR) is released two CCLK cycles after the DONE pin goes High. If CCLK is not clocked twice after DONE goes High, all flip-flops are held in their initial set or reset state. The delay from DONE High to GSR inactive is controlled by an option to the bitstream generation software.

### **Configuration Complete After DONE Goes High**

Three full CCLK cycles are required after the DONE pin goes High, as shown in [Figure 47 on page 53](#). If CCLK is not clocked three times after DONE goes High, readback cannot be initiated and most boundary scan instructions cannot be used.

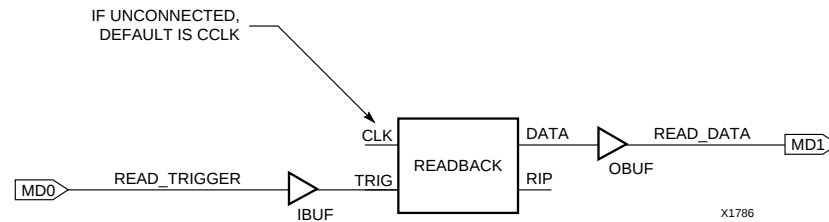
### **Configuration Through the Boundary Scan Pins**

XC4000 Series devices can be configured through the boundary scan pins. The basic procedure is as follows:

- Power up the FPGA with  $\overline{\text{INIT}}$  held Low (or drive the  $\overline{\text{PROGRAM}}$  pin Low for more than 300 ns followed by a High while holding  $\overline{\text{INIT}}$  Low). Holding  $\overline{\text{INIT}}$  Low allows enough time to issue the CONFIG command to the FPGA. The pin can be used as I/O after configuration if a resistor is used to hold  $\overline{\text{INIT}}$  Low.
- Issue the CONFIG command to the TMS input
- Wait for  $\overline{\text{INIT}}$  to go High
- Sequence the boundary scan Test Access Port to the SHIFT-DR state
- Toggle TCK to clock data into TDI pin.

The user must account for all TCK clock cycles after INIT goes High, as all of these cycles affect the Length Count compare.

For more detailed information, refer to the Xilinx application note XAPP017, “*Boundary Scan in XC4000 Devices*.” This application note also applies to XC4000E and XC4000X devices.



**Figure 49: Readback Schematic Example**

## Readback Options

Readback options are: Read Capture, Read Abort, and Clock Select. They are set with the bitstream generation software.

### Read Capture

When the Read Capture option is selected, the readback data stream includes sampled values of CLB and IOB signals. The rising edge of RDBK.TRIG latches the inverted values of the four CLB outputs, the IOB output flip-flops and the input signals I1 and I2. Note that while the bits describing configuration (interconnect, function generators, and RAM content) are *not* inverted, the CLB and IOB output signals *are* inverted.

When the Read Capture option is not selected, the values of the capture bits reflect the configuration data originally written to those memory locations.

If the RAM capability of the CLBs is used, RAM data are available in readback, since they directly overwrite the F and G function-table configuration of the CLB.

RDBK.TRIG is located in the lower-left corner of the device, as shown in [Figure 50](#).

### Read Abort

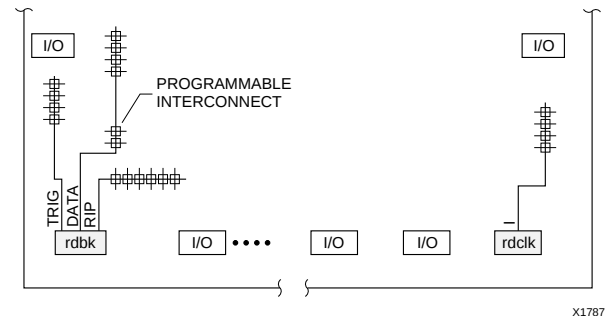
When the Read Abort option is selected, a High-to-Low transition on RDBK.TRIG terminates the readback operation and prepares the logic to accept another trigger.

After an aborted readback, additional clocks (up to one readback clock per configuration frame) may be required to re-initialize the control logic. The status of readback is indicated by the output control net RDBK.RIP. RDBK.RIP is High whenever a readback is in progress.

### Clock Select

CCLK is the default clock. However, the user can insert another clock on RDBK.CLK. Readback control and data are clocked on rising edges of RDBK.CLK. If readback must be inhibited for security reasons, the readback control nets are simply not connected.

RDBK.CLK is located in the lower right chip corner, as shown in [Figure 50](#).



**Figure 50: READBACK Symbol in Graphical Editor**

## Violating the Maximum High and Low Time Specification for the Readback Clock

The readback clock has a maximum High and Low time specification. In some cases, this specification cannot be met. For example, if a processor is controlling readback, an interrupt may force it to stop in the middle of a readback. This necessitates stopping the clock, and thus violating the specification.

The specification is mandatory only on clocking data at the end of a frame prior to the next start bit. The transfer mechanism will load the data to a shift register during the last six clock cycles of the frame, prior to the start bit of the following frame. This loading process is dynamic, and is the source of the maximum High and Low time requirements.

Therefore, the specification only applies to the six clock cycles prior to and including any start bit, including the clocks before the first start bit in the readback data stream. At other times, the frame data is already in the register and the register is not dynamic. Thus, it can be shifted out just like a regular shift register.

The user must precisely calculate the location of the readback data relative to the frame. The system must keep track of the position within a data frame, and disable interrupts before frame boundaries. Frame lengths and data formats are listed in [Table 19](#), [Table 20](#) and [Table 21](#).

## Readback with the XChecker Cable

The XChecker Universal Download/Readback Cable and Logic Probe uses the readback feature for bitstream verification. It can also display selected internal signals on the PC or workstation screen, functioning as a low-cost in-circuit emulator.

**Table 22: Pin Functions During Configuration**

| CONFIGURATION MODE <M2:M1:M0> |                          |                              |                               |                                 |                               | USER OPERATION |
|-------------------------------|--------------------------|------------------------------|-------------------------------|---------------------------------|-------------------------------|----------------|
| SLAVE SERIAL<br><1:1:1>       | MASTER SERIAL<br><0:0:0> | SYNCH. PERIPHERAL<br><0:1:1> | ASYNCH. PERIPHERAL<br><1:0:1> | MASTER PARALLEL DOWN<br><1:1:0> | MASTER PARALLEL UP<br><1:0:0> |                |
| M2(HIGH) (I)                  | M2(LOW) (I)              | M2(LOW) (I)                  | M2(HIGH) (I)                  | M2(HIGH) (I)                    | M2(HIGH) (I)                  | (I)            |
| M1(HIGH) (I)                  | M1(LOW) (I)              | M1(HIGH) (I)                 | M1(LOW) (I)                   | M1(HIGH) (I)                    | M1(LOW) (I)                   | (O)            |
| M0(HIGH) (I)                  | M0(LOW) (I)              | M0(HIGH) (I)                 | M0(HIGH) (I)                  | M0(LOW) (I)                     | M0(LOW) (I)                   | (I)            |
| HDC (HIGH)                    | HDC (HIGH)               | HDC (HIGH)                   | HDC (HIGH)                    | HDC (HIGH)                      | HDC (HIGH)                    | I/O            |
| LDC (LOW)                     | LDC (LOW)                | LDC (LOW)                    | LDC (LOW)                     | LDC (LOW)                       | LDC (LOW)                     | I/O            |
| INIT                          | INIT                     | INIT                         | INIT                          | INIT                            | INIT                          | I/O            |
| DONE                          | DONE                     | DONE                         | DONE                          | DONE                            | DONE                          | DONE           |
| PROGRAM (I)                   | PROGRAM (I)              | PROGRAM (I)                  | PROGRAM (I)                   | PROGRAM (I)                     | PROGRAM (I)                   | PROGRAM        |
| CCLK (I)                      | CCLK (O)                 | CCLK (I)                     | CCLK (O)                      | CCLK (O)                        | CCLK (O)                      | CCLK (I)       |
|                               |                          | RDY/BUSY (O)                 | RDY/BUSY (O)                  | RCLK (O)                        | RCLK (O)                      | I/O            |
|                               |                          |                              | RS (I)                        |                                 |                               | I/O            |
|                               |                          |                              | CS0 (I)                       |                                 |                               | I/O            |
|                               |                          | DATA 7 (I)                   | DATA 7 (I)                    | DATA 7 (I)                      | DATA 7 (I)                    | I/O            |
|                               |                          | DATA 6 (I)                   | DATA 6 (I)                    | DATA 6 (I)                      | DATA 6 (I)                    | I/O            |
|                               |                          | DATA 5 (I)                   | DATA 5 (I)                    | DATA 5 (I)                      | DATA 5 (I)                    | I/O            |
|                               |                          | DATA 4 (I)                   | DATA 4 (I)                    | DATA 4 (I)                      | DATA 4 (I)                    | I/O            |
|                               |                          | DATA 3 (I)                   | DATA 3 (I)                    | DATA 3 (I)                      | DATA 3 (I)                    | I/O            |
|                               |                          | DATA 2 (I)                   | DATA 2 (I)                    | DATA 2 (I)                      | DATA 2 (I)                    | I/O            |
|                               |                          | DATA 1 (I)                   | DATA 1 (I)                    | DATA 1 (I)                      | DATA 1 (I)                    | I/O            |
| DIN (I)                       | DIN (I)                  | DATA 0 (I)                   | DATA 0 (I)                    | DATA 0 (I)                      | DATA 0 (I)                    | I/O            |
| DOUT                          | DOUT                     | DOUT                         | DOUT                          | DOUT                            | DOUT                          | SGCK4-GCK6-I/O |
| TDI                           | TDI                      | TDI                          | TDI                           | TDI                             | TDI                           | TDI-I/O        |
| TCK                           | TCK                      | TCK                          | TCK                           | TCK                             | TCK                           | TCK-I/O        |
| TMS                           | TMS                      | TMS                          | TMS                           | TMS                             | TMS                           | TMS-I/O        |
| TDO                           | TDO                      | TDO                          | TDO                           | TDO                             | TDO                           | TDO-(O)        |
|                               |                          |                              | WS (I)                        | A0                              | A0                            | I/O            |
|                               |                          |                              |                               | A1                              | A1                            | PGCK4-GCK7-I/O |
|                               |                          |                              | CS1                           | A2                              | A2                            | I/O            |
|                               |                          |                              |                               | A3                              | A3                            | I/O            |
|                               |                          |                              |                               | A4                              | A4                            | I/O            |
|                               |                          |                              |                               | A5                              | A5                            | I/O            |
|                               |                          |                              |                               | A6                              | A6                            | I/O            |
|                               |                          |                              |                               | A7                              | A7                            | I/O            |
|                               |                          |                              |                               | A8                              | A8                            | I/O            |
|                               |                          |                              |                               | A9                              | A9                            | I/O            |
|                               |                          |                              |                               | A10                             | A10                           | I/O            |
|                               |                          |                              |                               | A11                             | A11                           | I/O            |
|                               |                          |                              |                               | A12                             | A12                           | I/O            |
|                               |                          |                              |                               | A13                             | A13                           | I/O            |
|                               |                          |                              |                               | A14                             | A14                           | I/O            |
|                               |                          |                              |                               | A15                             | A15                           | SGCK1-GCK8-I/O |
|                               |                          |                              |                               | A16                             | A16                           | PGCK1-GCK1-I/O |
|                               |                          |                              |                               | A17                             | A17                           | I/O            |
|                               |                          |                              |                               | A18*                            | A18*                          | I/O            |
|                               |                          |                              |                               | A19*                            | A19*                          | I/O            |
|                               |                          |                              |                               | A20*                            | A20*                          | I/O            |
|                               |                          |                              |                               | A21*                            | A21*                          | I/O            |
|                               |                          |                              |                               |                                 |                               | ALL OTHERS     |

## Master Parallel Modes

In the two Master Parallel modes, the lead FPGA directly addresses an industry-standard byte-wide EPROM, and accepts eight data bits just before incrementing or decrementing the address outputs.

The eight data bits are serialized in the lead FPGA, which then presents the preamble data—and all data that overflows the lead device—on its DOUT pin. There is an internal delay of 1.5 CCLK periods, after the rising CCLK edge that accepts a byte of data (and also changes the EPROM address) until the falling CCLK edge that makes the LSB (D0) of this byte appear at DOUT. This means that DOUT changes on the falling CCLK edge, and the next FPGA in the daisy chain accepts data on the subsequent rising CCLK edge.

The PROM address pins can be incremented or decremented, depending on the mode pin settings. This option allows the FPGA to share the PROM with a wide variety of microprocessors and micro controllers. Some processors must boot from the bottom of memory (all zeros) while others must boot from the top. The FPGA is flexible and can load its configuration bitstream from either end of the memory.

Master Parallel Up mode is selected by a <100> on the mode pins (M2, M1, M0). The EPROM addresses start at 00000 and increment.

Master Parallel Down mode is selected by a <110> on the mode pins. The EPROM addresses start at 3FFFF and decrement.

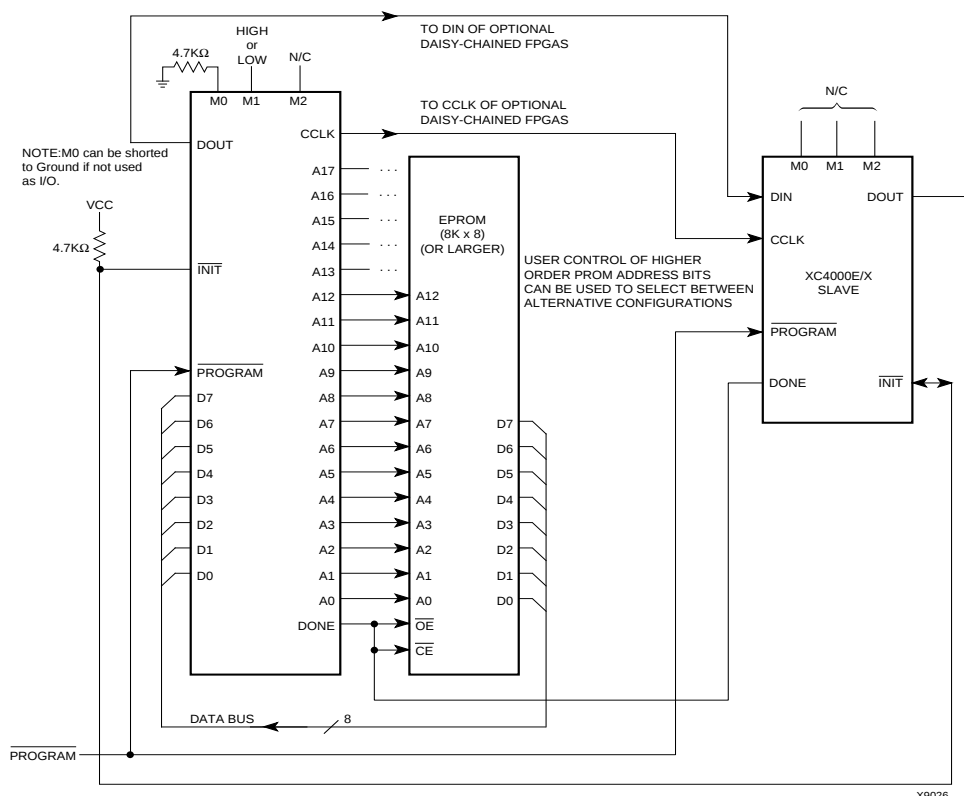
### Additional Address lines in XC4000 devices

The XC4000X devices have additional address lines (A18-A21) allowing the additional address space required to daisy-chain several large devices.

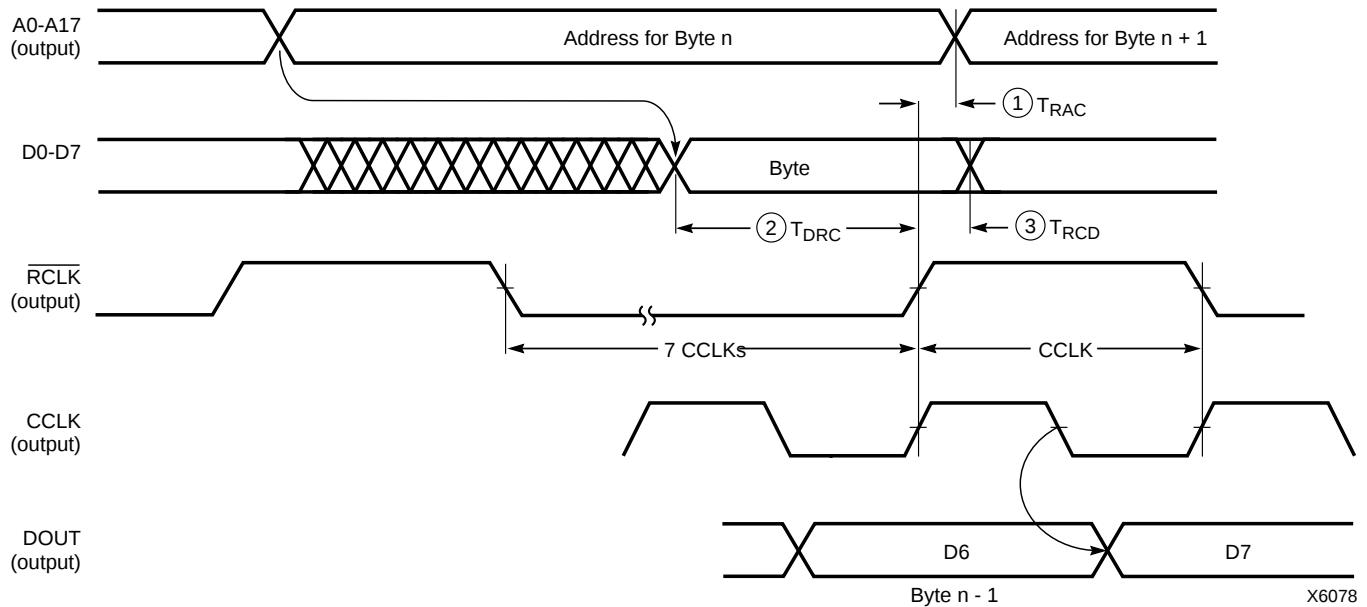
The extra address lines are programmable in XC4000EX devices. By default these address lines are not activated. In the default mode, the devices are compatible with existing XC4000 and XC4000E products. If desired, the extra address lines can be used by specifying the address lines option in bitgen as 22 (bitgen -g AddressLines:22). The lines (A18-A21) are driven when a master device detects, via the bitstream, that it should be using all 22 address lines. Because these pins will initially be pulled high by internal pull-ups, designers using Master Parallel Up mode should use external pull down resistors on pins A18-A21. If Master Parallel Down mode is used external resistors are not necessary.

All 22 address lines are always active in Master Parallel modes with XC4000XL devices. The additional address lines behave identically to the lower order address lines. If the Address Lines option in bitgen is set to 18, it will be ignored by the XC4000XL device.

The additional address lines (A18-A21) are not available in the PC84 package.



**Figure 54: Master Parallel Mode Circuit Diagram**



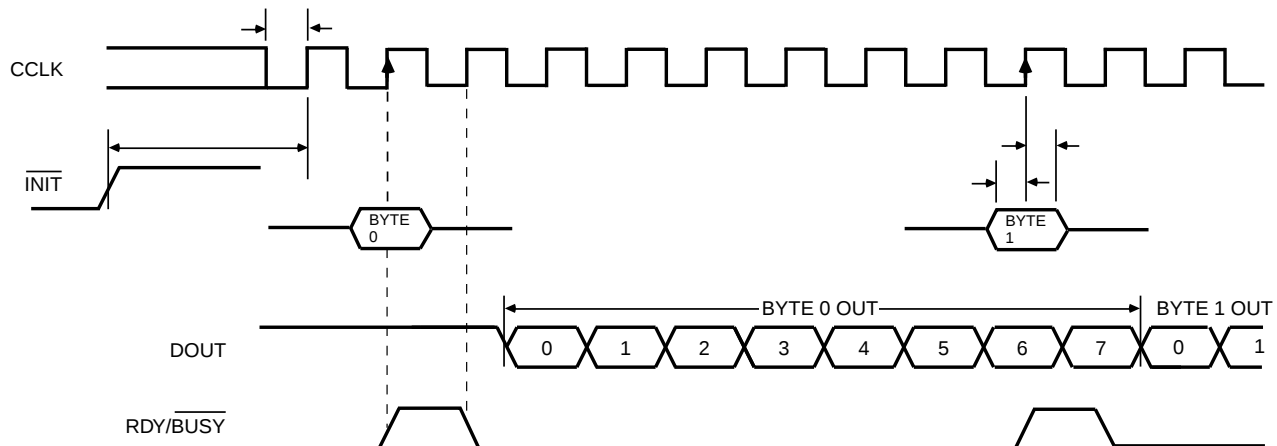
|      | Description            | Symbol      | Min | Max | Units |
|------|------------------------|-------------|-----|-----|-------|
| RCLK | Delay to Address valid | 1 $T_{RAC}$ | 0   | 200 | ns    |
|      | Data setup time        | 2 $T_{DRC}$ | 60  |     | ns    |
|      | Data hold time         | 3 $T_{RCD}$ | 0   |     | ns    |

Notes: 1. At power-up,  $V_{cc}$  must rise from 2.0 V to  $V_{cc}$  min in less than 25 ms, otherwise delay configuration by pulling PROGRAM Low until  $V_{cc}$  is valid.

2. The first Data byte is loaded and CCLK starts at the end of the first RCLK active cycle (rising edge).

This timing diagram shows that the EPROM requirements are extremely relaxed. EPROM access time can be longer than 500 ns. EPROM data output has no hold-time requirements.

**Figure 55: Master Parallel Mode Programming Switching Characteristics**



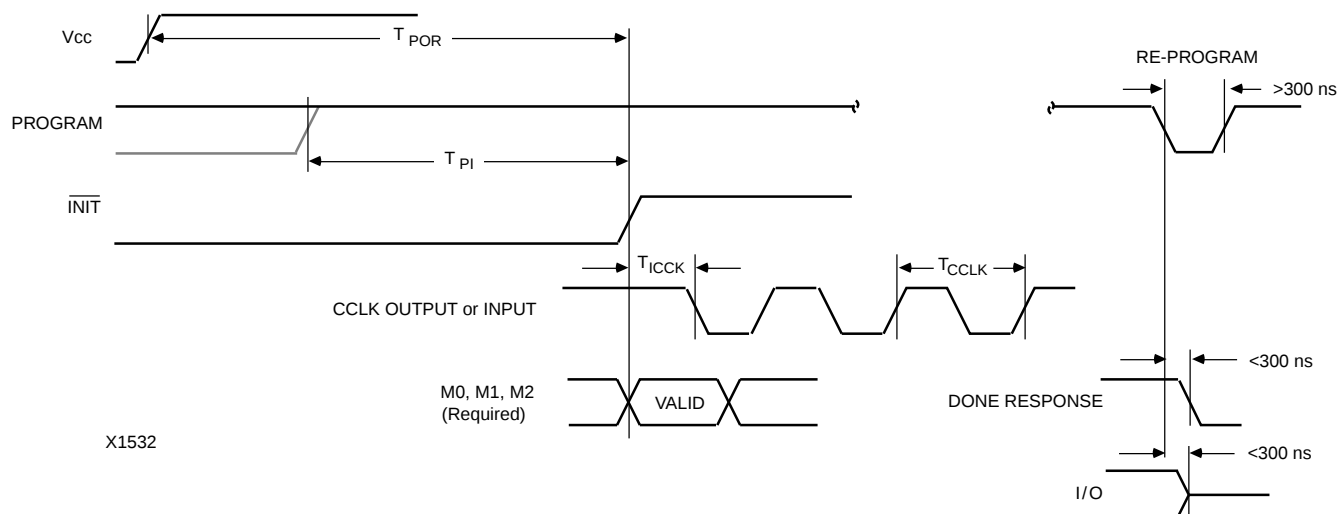
X6096

|      | Description            | Symbol    | Min | Max | Units   |
|------|------------------------|-----------|-----|-----|---------|
| CCLK | INIT (High) setup time | $T_{IC}$  | 5   |     | $\mu s$ |
|      | D0 - D7 setup time     | $T_{DC}$  | 60  |     | ns      |
|      | D0 - D7 hold time      | $T_{CD}$  | 0   |     | ns      |
|      | CCLK High time         | $T_{CCH}$ | 50  |     | ns      |
|      | CCLK Low time          | $T_{CCL}$ | 60  |     | ns      |
|      | CCLK Frequency         | $F_{CC}$  |     | 8   | MHz     |

- Notes:
1. Peripheral Synchronous mode can be considered Slave Parallel mode. An external CCLK provides timing, clocking in the **first** data byte on the **second** rising edge of CCLK after INIT goes High. Subsequent data bytes are clocked in on every eighth consecutive rising edge of CCLK.
  2. The RDY/BUSY line goes High for one CCLK period after data has been clocked in, although synchronous operation does not require such a response.
  3. The pin name RDY/BUSY is a misnomer. In Synchronous Peripheral mode this is really an ACKNOWLEDGE signal.
  4. Note that data starts to shift out serially on the DOUT pin 0.5 CCLK periods after it was loaded in parallel. Therefore, additional CCLK pulses are clearly required after the last byte has been loaded.

**Figure 57: Synchronous Peripheral Mode Programming Switching Characteristics**

## Configuration Switching Characteristics



X1532

### Master Modes (XC4000E/EX)

| Description                |           | Symbol     | Min | Max  | Units                  |
|----------------------------|-----------|------------|-----|------|------------------------|
| Power-On Reset             | M0 = High | $T_{POR}$  | 10  | 40   | ms                     |
|                            | M0 = Low  | $T_{POR}$  | 40  | 130  | ms                     |
| Program Latency            |           | $T_{PI}$   | 30  | 200  | $\mu s$ per CLB column |
| CCLK (output) Delay        |           | $T_{ICCK}$ | 40  | 250  | $\mu s$                |
| CCLK (output) Period, slow |           | $T_{CCLK}$ | 640 | 2000 | ns                     |
| CCLK (output) Period, fast |           | $T_{CCLK}$ | 80  | 250  | ns                     |

### Master Modes (XC4000XL)

| Description                |           | Symbol     | Min | Max  | Units                  |
|----------------------------|-----------|------------|-----|------|------------------------|
| Power-On Reset             | M0 = High | $T_{POR}$  | 10  | 40   | ms                     |
|                            | M0 = Low  | $T_{POR}$  | 40  | 130  | ms                     |
| Program Latency            |           | $T_{PI}$   | 30  | 200  | $\mu s$ per CLB column |
| CCLK (output) Delay        |           | $T_{ICCK}$ | 40  | 250  | $\mu s$                |
| CCLK (output) Period, slow |           | $T_{CCLK}$ | 540 | 1600 | ns                     |
| CCLK (output) Period, fast |           | $T_{CCLK}$ | 67  | 200  | ns                     |

### Slave and Peripheral Modes (All)

| Description                    |  | Symbol     | Min | Max | Units                  |
|--------------------------------|--|------------|-----|-----|------------------------|
| Power-On Reset                 |  | $T_{POR}$  | 10  | 33  | ms                     |
| Program Latency                |  | $T_{PI}$   | 30  | 200 | $\mu s$ per CLB column |
| CCLK (input) Delay (required)  |  | $T_{ICCK}$ | 4   |     | $\mu s$                |
| CCLK (input) Period (required) |  | $T_{CCLK}$ | 100 |     | ns                     |

